

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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www.SunLEDusa.com

Part Number: XZRNI56W-1

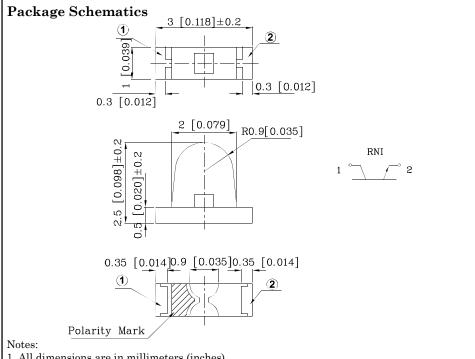
PHOTOTRANSISTOR

Features

- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 3
- ullet RoHS compliant







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Condiction
VBR CEO	Collector-to-Emitter Breakdown Voltage	30			V	Ic=100μA Ee=0mW/cm²
VBR ECO	Emitter-to-Collector Breakdown Voltage	5			V	IE=100μA Ee=0mW/cm²
VCE(SAT)	Collector-to-Emitter Saturation Voltage			0.8	V	IC=2mA Ee=20mW/cm²
ICEO	Collector Dark Current			100	nA	VCE=10V Ee=0mW/cm ²
TR	Rise Time (10% to 90%)		15		μs	Vc=5V Ic=1mA RL=1KΩ
TF	Fall Time (90% to 10%)		15		μs	
I(ON)	On State Collector Current	0.2	0.5		mA	$V_{CE}=5V$ $Ee=1mW/cm^2$ $\lambda=940nm$

Absolute Maximum Ratings at TA=25°C

Parameter	Maximum Ratings		
Collector-to-Emitter Voltage	30V		
Emitter-to-Collector Voltage	5V		
Power Dissipation at (or below) 25°C Free Air Temperature	100mW		
Operating / Storage Temperature Range	-40°C To +85°C		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Mar 28, 2016





Typical Electro-Optical Characteristics Curves

 $\begin{array}{ccc} Fig.1 & Collector & Power & Dissipation & vs. \\ & & Ambient Temperature \\ \end{array}$

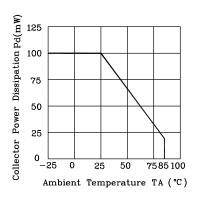
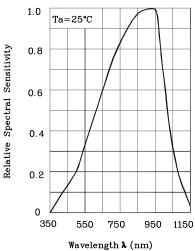


Fig.2 Spectral Sensitivity



 $\begin{array}{cccc} \textbf{Fig.3 Relative Collector Current vs.} \\ \textbf{Ambient Temperature} \end{array}$

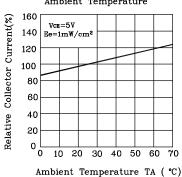
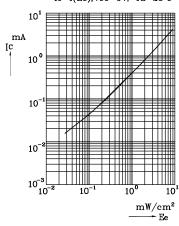


Fig. 4 Collector Current Ic=f(Ec),Vce=5V, Ta=25°C



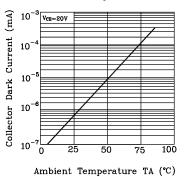
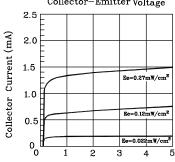
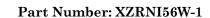


Fig. 6 CollectorCurrent vs.

Collector-Emitter Voltage



Collector-Emitter Voltage VCE (V)



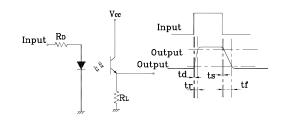




PHOTOTRANSISTOR

Fig.7 Response Time vs. Load Resistance 100 Vce=5V (sn) k=100 uA Ta=25°C Response time 0.010.1 10 Load Resistance R. (ka)

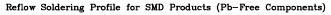
Test Circuit for Response Time

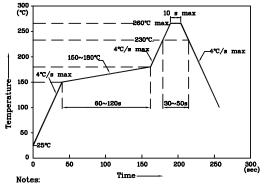


❖ LED is recommended for reflow soldering and soldering profile is shown below.

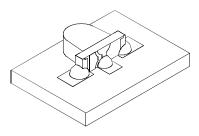
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❖ The device has a single mounting surface. The device must be mounted according to the specifications.

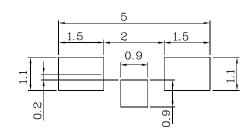




- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions



❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

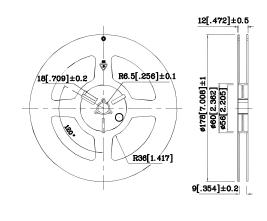


❖ Tape Specification (Units: mm)

4.0 ± 0.1 1.75 ± 0.1 $\phi 1.5 \pm 0.1$ 4.0±0.1 1.15±0.1 2.0 ± 0.1 0.23 ± 0.1 5±0.05 8.0 ± 0.3

TAPE

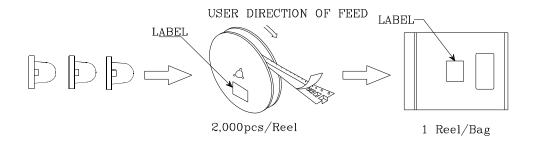
❖ Reel Dimension

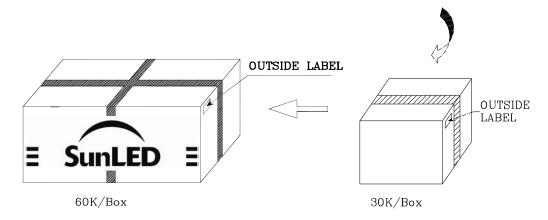


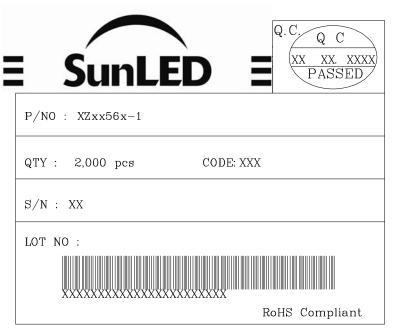




PACKING & LABEL SPECIFICATIONS







TERMS OF USE

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- $2. \ Contents \ within \ this \ document \ are \ subject \ to \ improvement \ and \ enhancement \ changes \ without \ notice.$
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